


DMSMS NOTICE

DIMINISHING MANUFACTURING SOURCES AND MATERIAL SHORTAGES

1. TITLE END OF LIFE AND REPLACEMENT DEVICE NOTIFICATION FOR MRAM PRODUCTION DUE TO PROCESS AND QUALIFICATION CHANGES		2. DOCUMENT NUMBER SPO-2019-D-0010													
		3. DATE (Year, Month, Date) 2019, June 26													
4. MANUFACTURER NAME AND ADDRESS CAES 4350 CENTENNIAL BOULEVARD COLORADO SPRINGS, COLORADO 80907-3486		5. MANUFACTURER POINT OF CONTACT (NAME) Mike Leslie													
		6. MANUFACTURER POINT OF CONTACT TELEPHONE 719-594-8148													
		7. MANUFACTURER POINT OF CONTACT EMAIL Mike.Leslie@cobhamaes.com													
8. CAGE CODE 65342	9. MANUFACTURER FINAL ORDER DATE	10. PRODUCT IDENTIFICATION CODE WP01	11. BASE PART UT8MR2M8												
12. BLANK		13. SMD NUMBER 5962-12227	14. DEVICE TYPE DESIGNATOR 01, 02												
		15. RHA LEVELS H	16. QML LEVEL Q, Q+, V												
		17. NON QML LEVEL Proto, HiRel	18. GIDEP NUMBER GB4-D-19_0008												
19. COMMENTS CAES IS ISSUING THIS DIMINISHING MANUFACTURING SOURCES AND MATERIAL SHORTAGES NOTICE TO ANNOUNCE END OF LIFE (EOL) OF THE CURRENT MRAM DEVICE TYPE OFFERINGS AND ADDING REPLACEMENT DEVICE TYPES BASED ON PROCESS AND QUALIFICATION FLOW CHANGES AS NOTED BELOW: DEVICE TYPES 01 AND 02 WILL NO LONGER BE AVAILABLE AS OF THIS NOTIFICATION. NEW DEVICE TYPES 03 AND 04 WILL REPLACE THEM WITH THE EXCEPTIONS NOTED BELOW. <u>ADD DEVICE TYPES 03 AND 04 TO SECTION 1.2.2 (PAGE 2)</u> <table border="1"> <thead> <tr> <th>Device type</th> <th>Generic number</th> <th>Circuit function</th> <th>Access time</th> </tr> </thead> <tbody> <tr> <td>03</td> <td>UT8MR2M8</td> <td>2M X 8-bit rad-hard MRAM <u>2/</u></td> <td>45ns</td> </tr> <tr> <td>04</td> <td>UT8MR2M8</td> <td>2M X 8-bit rad-hard MRAM <u>1/ 2/</u></td> <td>45ns</td> </tr> </tbody> </table> <u>DEVICE TYPE 04 ADDED TO NOTE 1/ ON PAGE 2.</u> <u>DEVICE TYPE 03 AND 04 ADDS NOTE 2/ TO SMD PAGE 2.</u> <u>2/ DEVICE TYPE 03 AND 04 INCLUDE COLD WAFER PROBE (-40C) AS PART OF THE PRODUCTION FLOW.</u> <u>DEVICE TYPE 04 ADDED TO 4.2.1d (page 22)</u> Additional screening for device types 02 and 04 <u>CHANGE ITEM (6) OF 4.2.1d (page 22):</u> Dynamic burn-in at +125°C for 240 hours or equivalent and static burn-in at +125C for 144 hours (device type 04 only, method 1015 of MIL-STD-883), deltas, PDA (3%) for Functional Test only, and PDA (5%) for DC and Functional Test combined. <u>DEVICE TYPE 04 ADDED TO NOTE 6/ TABLE IIA (page 24)</u> Continued on sheet 2				Device type	Generic number	Circuit function	Access time	03	UT8MR2M8	2M X 8-bit rad-hard MRAM <u>2/</u>	45ns	04	UT8MR2M8	2M X 8-bit rad-hard MRAM <u>1/ 2/</u>	45ns
Device type	Generic number	Circuit function	Access time												
03	UT8MR2M8	2M X 8-bit rad-hard MRAM <u>2/</u>	45ns												
04	UT8MR2M8	2M X 8-bit rad-hard MRAM <u>1/ 2/</u>	45ns												
20. ADEPT REPRESENTATIVE Lin-Chi Huang		21. SIGNATURE 													
		22. DATE yyyy, February, dd													

NOTE 3/ ADDED TO STANDARD MICROCIRCUIT DRAWING BULLETIN AND NOTED ON VENDOR CAGE NUMBER FOR ALL DEVICE TYPES 01 AND 02

3/ NOT AVAILABLE FROM AND APPROVED SOURCE OF SUPPLY

ADD DEVICE TYPE 03 AND 04 TO 5962-12227 SMD BULLETIN PAGE AS BELOW:

5962H1222703QXC	65342	UT8MR2M8-40XQC
5962H1222703QYC	65342	UT8MR2M8-40YQC
5962H1222704QXC	65342	UT8MR2M8-40XQC
5962H1222704QYC	65342	UT8MR2M8-40YQC